

IEEE COINS 2021

IEEE International Conference on Omni-layer Intelligent Systems

IEEE | IEEE RAS | IEEE CEDA | IEEE COMPUTER SOCIETY | VSA-TC IEEE CAS | E-HEALTH-TC IEEE COMSOC | TC-ICPS IEEE IES | IEEE IOT

Hybrid Event:
(On-site In-person Presentation & Virtual Presentation)

Barcelona, Spain
August 23-25, 2021



Call for Papers

IEEE COINS includes a multi-disciplinary program from technical research papers, to panels, workshops, and tutorials on the latest technology developments and innovations. IEEE COINS will address all important aspects of the IoT ecosystem. IEEE COINS solicits papers and proposals accompanying submissions for presentations in the Vertical and Topical Tracks.

Topical Area Tracks:

- 1) Internet of Things: From Device, to Edge, and Cloud
- 2) Sensors and Sensing Systems
- 3) Circuits and Systems for Artificial Intelligence, and Internet of Things
- 4) Communications, Connectivity, and Networking
- 5) Big Data, Data Engineering, and Data Analytics
- 6) Artificial Intelligence, Machine Learning, and Cognitive Computing
- 7) Distributed Ledger Technologies and Blockchain
- 8) Design Automation in AI & IoT Era: From Chips to Systems
- 9) Hardware/Cyber Security and Privacy
- 10) Intelligent Robots and Systems
- 11) Applications, Processes, and Services

Vertical Tracks:

- 1) Smart City
- 2) Industry 4.0
- 3) e-Health and Wearable IoT
- 4) Agri-Tech
- 5) Smart Energy

Special Tracks:

- 1) Critical System Design
- 2) European Projects on Intelligent Systems
- 3) Emerging Technologies on intelligent systems
- 4) Cognitive Environment
- 5) Machine Learning/Artificial Intelligence Techniques for IoT networks of Smart Cities based on Edge to Cloud orchestration
- 6) Clinical Decision Support System for supporting COVID-19 pandemic
- 7) Semantic Interoperability for IoT

IEEE COINS will publish accepted papers in the conference proceedings and the proceedings will be submitted to the IEEE Xplore Digital library and indexing services.

Selected best contributions of IEEE COINS will be invited to submit expanded versions of their studies to IEEE IoTJ (IF=9.936) for review and potential publication.

 Submission of Regular Papers and Special Session Papers
April 30, 2021

 Notification of Paper Acceptance
June 30, 2021

Conference Board

Krishnendu Chakrabarty, Duke University
Jan M. Rabaey, UC Berkeley
David Z. Pan, University of Texas at Austin
Majid Sarrafzadeh, UCLA
Farshad Firouzi, Duke University

General Chairs

Farshad Firouzi, Duke University
Krishnendu Chakrabarty, Duke University

Technical Chairs

Hadi Heidari, University of Glasgow
Bahar Farahani, Cyberspace Research Institute
Naghme Karimi, University of Maryland, Baltimore County

Local Chairs

Jose Ayala, Complutense University of Madrid

Publication Chairs

Vassos Soteriou, Cyprus University of Technology

Publicity Chairs

Xueqing Li, Tsinghua University
Masoumeh (Azin) Ebrahimi, KTH Royal Institute of Technology
Fatemeh Afghah, Northern Arizona University
Ye Liu, NJAU

Track Chairs

Yuanqing Cheng, Beihang University, China
Fatemeh Afghah, Northern Arizona University
JOSé Manuel Benitez, University of Granada, Spain
Sebastian Ventura, University of Córdoba, Spain
Yongy Ran, Nanyang Technological University, Singapore
Jiang Li, Shanghai Jiaotong University, China
Maria K. Michael, University of Cyprus, Cyprus
Amir Rahmani, University of California Irvine, USA
Kun-Chih Chen (Jimmy), National Sun Yat-Sen University, Taiwan
Chung-Wei Lin, National Taiwan University, Taiwan
Xing Liu, Kwantlen Polytechnic University, Canada
Kim Grütner, OFFIS, Germany
Max Pfingsthorn, Offis, Germany
Wanli Chang, University of York, UK
Chen Xianfu, VTT, Finland
Marina Zapater Sancho, EPFL, Switzerland
Andrea Sciarone, University of Geneva, Switzerland
Han Hu, Beijing Institute of Technology, China
Jorge Rocha, University of Lisbon, Portugal
Xavier Bellekens, University of Strathclyde, UK
Mian Ahmad Jan, Abdul Wali Khan University Mardan, Pakistan
Fazlullah Khan, Rozetta Institute, Sydney Australia
Nadeem Iqbal, Abdul Wali Khan University Mardan, Pakistan
Spyridon Mastorakis, University of Nebraska Omaha, United States
Varun G Menon, SCMS School of Engineering and Technology
Jean-Luc Danger, Telecom ParisTech, France
Syed Hassan Ahmed, JMA Wireless, USA
Valeria Loscri, Inria Lille – Nord Europe, France
Giuseppe Ruggeri, University "Mediterranea" of Reggio Calabria, Italy
Teresa Serrano-Gotarredona, National Microelectronics Center (IMSE-CNM-CSIC) Sevilla, Spain
Michele Lora, University of Verona, Italy